L Number	Hits	Search Text	DB	Time stamp
78	1	("6602620").PN.	USPAT	2003/11/10 11:02
79	1	6602620.pn. and non-magnetic with	USPAT	2003/11/10
80	0	coercivity and magnetic with coercivity non-magnertic with coercive	USPAT	2003/11/10 11:05
81	385	non-magnetic with coercive	USPAT	2003/11/10
-	1396	mask with pattern with magnetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05
-	325	(mask with pattern with magnetic same layer record\$3 and pholithography and plasma and etch\$3 and lithography) and @ad<20000419	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/06 10:00
_	102	((mask with pattern with magnetic same layer record\$3 and pholithography and plasma and etch\$3 and lithography) and @ad<20000419) and (disc disk)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05 14:42
_	107	((mask with pattern with magnetic same layer record\$3 and pholithography and plasma and etch\$3 and lithography) and @ad<20000419) and (disc disk)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05 14:43
-	0	mask with pattern with magnetic same layer with record\$3 and pholithography and plasma and etch\$3 and lithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05 14:45
-	0	mask with pattern with magnetic same layer and pholithography and plasma and etch\$3 and lithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05 14:44
-	. 0	mask with pattern with magnetic same layer and pholithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/05 14:44
-	0	mask with pattern with magnetic and pholithography and plasma and etch\$3 and lithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05
-	0	mask with pattern with magnetic and pholithography and plasma and etch\$3 and lithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05 14:46
-	1117	mask with pattern with magnetic and (pholithography and plasma etch\$3 lithography)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05 14:47
_	62	mask with pattern with magnetic and (pholithography same plasma pholithography same etch\$3 lithography same plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05 14:49
_	18	(mask with pattern with magnetic and (pholithography same plasma pholithography same etch\$3 lithography same plasma)) and @ad<20000419	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/05 14:50

-	10	((mask with pattern with magnetic and	USPAT;	2003/11/05
		(pholithography same plasma pholithography same etch\$3 lithography	US-PGPUB;	14:55
		same plasma)) and @ad<20000419) and (disc	EPO; JPO; DERWENT;	
		disk)	IBM TDB	
_	10	1 \ · · · · · · · · · · · · · · · · · ·	USPAT;	2003/11/05
		(pholithography same plasma	US-PGPUB;	14:56
		pholithography same etch\$3 lithography	EPO; JPO;	
		same plasma)) and @ad<20000419) and (disc	DERWENT;	
	9	disk)	IBM_TDB USPAT;	2003/11/06
-	9	(mask with pattern with magnetic same layer and (pholithography same plasma	US-PGPUB;	10:01
		plasma same etch\$3 and lithography same	EPO; JPO;	10.01
		etch\$3)) and @ad<20000419	DERWENT;	
			IBM_TDB	
-	75	1	USPAT;	2003/11/06
1		layer and (pholithography same plasma	US-PGPUB;	15:18
		plasma same etch\$3 lithography same etch\$3)) and @ad<20000419	EPO; JPO; DERWENT;	
		ecchiquy) and ead(20000419	IBM TDB	
_	0	6602620.pn. and block with mask	USPAT;	2003/11/06
]	•	US-PGPUB;	12:35
			EPO; JPO;	
			DERWENT;	
	2	(mack with mattern with magnetic came	IBM_TDB USPAT;	2003/11/06
-		(mask with pattern with magnetic same layer and stamp\$3 and (plasma same	USPAT; US-PGPUB;	2003/11/06
		etch\$3)) and @ad<20000419	EPO; JPO;	13.20
			DERWENT;	
			IBM_TDB	
-	158		USPAT;	2003/11/06
		(plasma same etch\$3)) and @ad<20000419	US-PGPUB;	15:21
			EPO; JPO; DERWENT;	
			IBM TDB	
_	36	(mask with pattern same stamp\$3 and	USPAT;	2003/11/06
		(plasma same etch\$3)) and @ad<20000419	US-PGPUB;	15:47
			EPO; JPO;	
			DERWENT;	
l _	0	(mask with pattern same stamp\$3 and	IBM_TDB USPAT;	2003/11/06
		(plasma same etch\$3)) and @ad<20000419	US-PGPUB;	16:00
		and magnet	EPO; JPO;	10.00
			DERWENT;	
			IBM_TDB	
-	0	\	USPAT;	2003/11/06
1		(plasma same etch\$3)) and @ad<20000419 and magnet\$%3	US-PGPUB; EPO; JPO;	16:00
1		and magnety of	DERWENT;	
			IBM_TDB	
_	15	1 '	USPAT;	2003/11/06
1		(plasma same etch\$3)) and @ad<20000419	US-PGPUB;	16:29
1	-	and magnet\$3	EPO; JPO;	
			DERWENT; IBM TDB	
_	307	(mask with pattern same (compress\$3	USPAT;	2003/11/06
		press\$3 stamp\$3) and (plasma same	US-PGPUB;	16:32
		etch\$3)) and @ad<20000419 and magnet\$3	EPO; JPO;	
			DERWENT;	
1_	,	(magk with nattown some (see-see-see)	IBM_TDB	2002/11/06
-	7	(mask with pattern same (compress\$3) and (plasma same etch\$3)) and @ad<20000419	USPAT; US-PGPUB;	2003/11/06 116:32
1		and magnet\$3	EPO; JPO;	10.32
			DERWENT;	
			IBM_TDB	
-	15		USPĀT;	2003/11/07
		(plasma same etch\$3)) and @ad<20000419	US-PGPUB;	10:19
]		and magnet\$\$3	EPO; JPO;	
	:		DERWENT; IBM TDB	
		<u> </u>		<u></u>



-	7	(mask with pattern same compress\$3 and	USPAT;	2003/11/07
		(plasma same etch\$3)) and @ad<20000419	US-PGPUB;	10:20
		and magnet\$\$3	EPO; JPO;	1
	į		DERWENT;	
			IBM_TDB	
-	78	mask with pattern same compress\$3 and	USPAT;	2003/11/10
		@ad<20000419 and magnet\$3	US-PGPUB;	09:22
			EPO; JPO;	
1			DERWENT;	
1			IBM TDB	
	l 0	428/694.ccls. and mask same pattern	USPAT;	2003/11/10
		-	US-PGPUB;	09:23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	428/694.ccls. and mask	USPAT;	2003/11/10
			US-PGPUB;	09:23
			EPO; JPO;	
}			DERWENT;	İ
			IBM TDB	
_	l o	428/694.ccls.	USPAT;	2003/11/10
			US-PGPUB;	09:24
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	17	428/694r.ccls. and mask same pattern	USPAT;	2003/11/10
			US-PGPUB;	10:10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	42	compress with mask same pattern	USPAT;	2003/11/10
	'-	The state of the s	US-PGPUB;	10:55
			EPO; JPO;	
			DERWENT;	
			IBM TDB	